

Date: 5th September 2023

№ 202301027

Non-compliant product information

The substance listed below may potentially contain above 0.1% by weight (w/w) per Components Article.

Substance Name	CAS No.	Remarks
Lead	7439-92-1	Note 1 : Chip-R , <5% , RoHS exemption 7(c)-I.
2-Methyl-1-(4-methylthiophenyl)-2-morpholinopropan-1-one	71868-10-5	Note 2 : PCB Solder Mask , < 5%.
1,3,5-Tris(oxiran-2-ylmethyl)-1,3,5-triazinane-2,4,6-trione (TGIC)	2451-62-9	Note 3 : PCB Solder Mask , < 3.3%.
Melamine	108-78-1	Note 4 : PCB Solder Mask , < 10%.

Part Number	Contains SVHC (> 0.1%)	Note No.	CAS No.	Description of Use
EXC7237	Yes	Note 1 Note 2 Note 3 Note 4	7439-92-1 71868-10-5 2451-62-9 108-7-1	Chip-R. PCB-Solder Mask. PCB-Solder Mask. PCB-Solder Mask.

[Note 1.](#) Chip-Resistor contains <5 wt% of Lead(Pb) in Resistive layer as Glass frit. Lead may contain >0.1 wt% in Components Article. Compliance with RoHS exemption 7(c)-I.

▲ 7(c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

[Note 2.](#) PCB contains <5 wt% of 2-Methyl-1-(4-methylthiophenyl)-2-morpholinopropan-1-one in Solder Mask as Photoinitiator. Substance may contain max 6300ppm in Pre-baked ink.

[Note 3.](#) PCB contains max 3.3 wt% of Triglycidyl isocyanurate in Solder Mask as hardener. Substance may contain <1000ppm in Pre-baked ink.

[Note 4.](#) PCB contains <10 wt% of Melamine in Solder Mask as hardener. Substance may contain max 5200ppm in Pre-baked ink.